
HVM14S

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

HITACHI

ADE-208-083D(Z)

Rev. 4
Feb. 1999

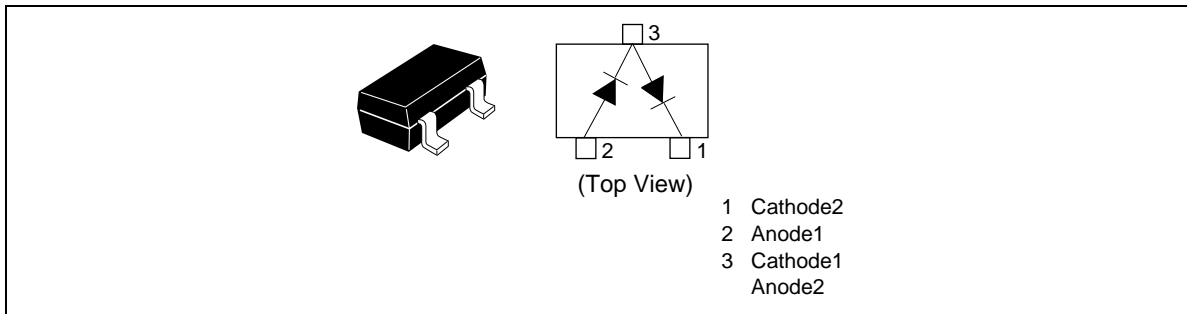
Features

- Low forward resistance. ($r_f = 7.0\Omega_{\max}$)
- Low capacitance. ($C = 0.25\text{pF typ}$)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVM14S	H6	MPAK

Outline



HVM14S

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	50	V
Forward current	I_F	50	mA
Power dissipation	P_d^{*1}	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55to+125	°C

Note: 1. Two device total.

Electrical Characteristics ^{*2}

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	1.0	V	$I_F = 50 \text{ mA}$
Reverse current	I_R	—	—	100	nA	$V_R = 50\text{V}$
Capacitance	C	—	0.25	—	pF	$V_R = 50\text{V}, f = 1 \text{ MHz}$
Forward resistance	r_f	—	—	7	Ω	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$
ESD-Capability ^{*1}	—	200	—	—	V	C=200pF, Both forward and reverse direction 1 pulse

Note: 1. Failure criterion ; $I_R \geq 200\text{nA}$ at $V_R = 50 \text{ V}$

Note: 2. Per one device.

Main Characteristic

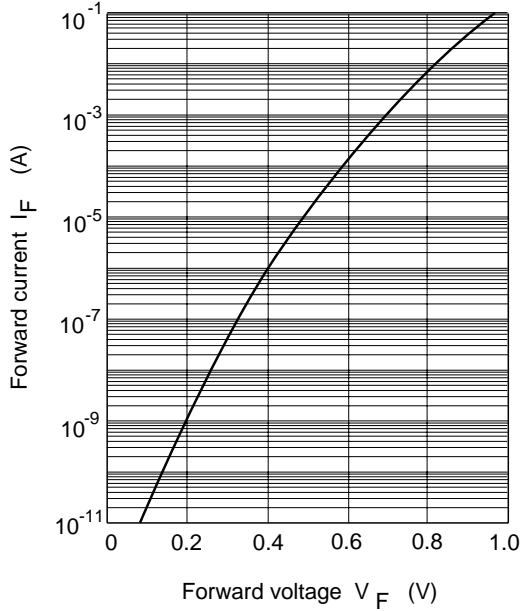


Fig.1 Forward current Vs. Forward voltage

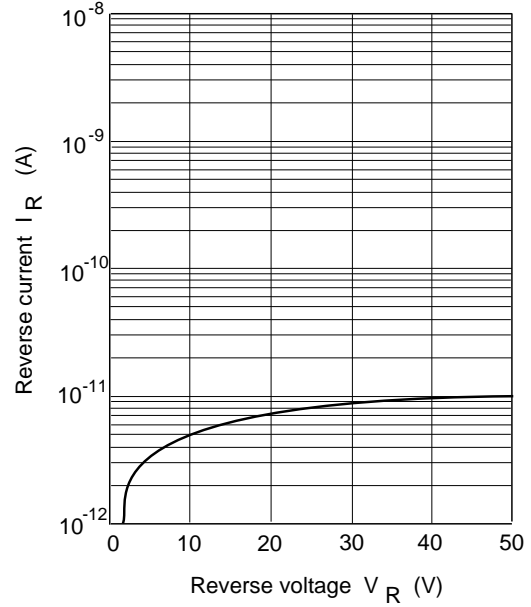


Fig.2 Reverse current Vs. Reverse voltage

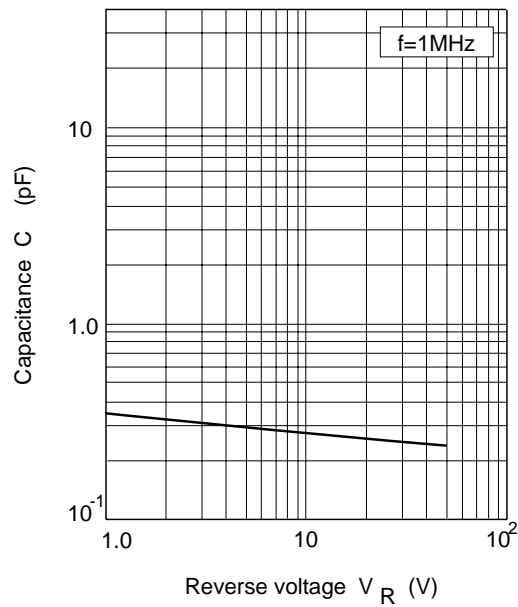


Fig.3 Capacitance Vs. Reverse voltage

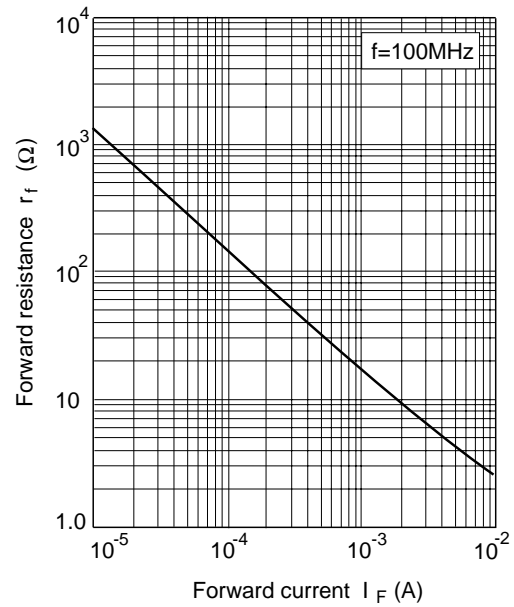
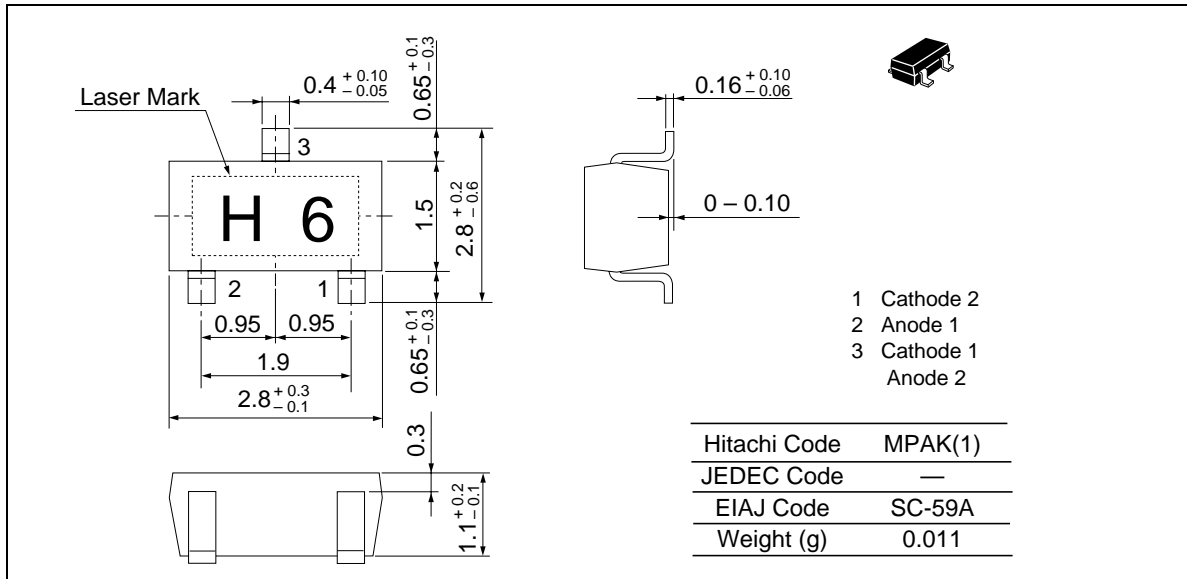


Fig.4 Forward resistance Vs. Forward current

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Package Dimensions

Unit : mm



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Sales Offices

HITACHI**Hitachi, Ltd.**

Semiconductor & Integrated Circuits
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
 Asia : <http://sicapac.hitachi-asia.com>
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe Ltd.
Electronic Components Group
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 585200

Hitachi Europe GmbH
Electronic Components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Asia Ltd.
Hitachi Tower
16 Collyer Quay #20-00
Singapore 049318
Tel: <65>-538-6533/538-8577
Fax: <65>-538-6933/538-3877
URL: <http://www.hitachi.com.sg>

Hitachi Asia Ltd.
(Taipei Branch Office)
4/F, No. 167, Tun Hwa North Road
Hung-Kuo Building
Taipei (105), Taiwan
Tel: <886>-(2)-2718-3666
Fax: <886>-(2)-2718-8180
Telex: 23222 HAS-TP
URL: <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon
Hong Kong
Tel: <852>-(2)-735-9218
Fax: <852>-(2)-730-0281
URL: <http://semiconductor.hitachi.com.hk>

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